

GaAs HIGH POWER T-1 3/4 PACKAGE INFRARED EMITTING DIODE

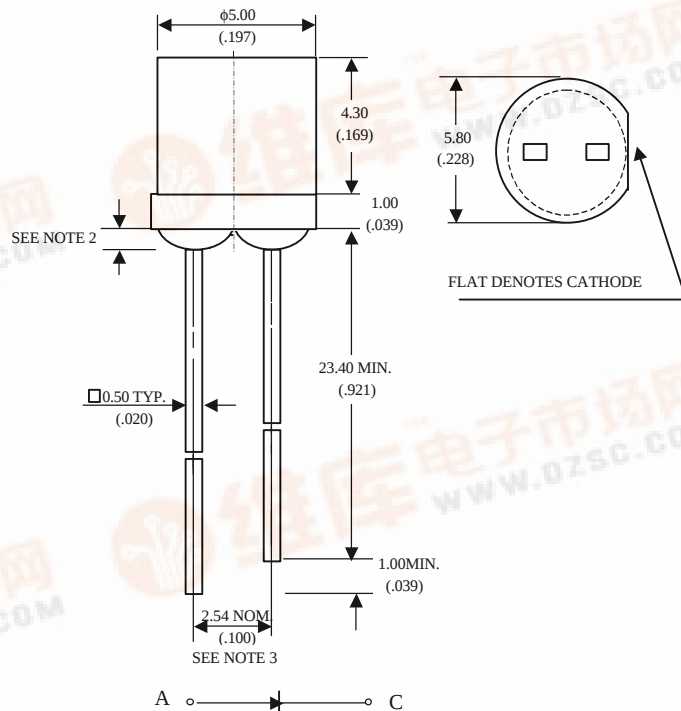
MIE-824L3

Description

The MIE-824L3 is an infrared emitting diode utilizing GaAs with AlGaAs window coation chip technology. It is molded in water clear plastic package.

Package Dimensions

Unit: inches



Features

- High radiant power and high radiant intensity
- Standard T-1 3/4 (ϕ 5mm) package
- Peak wavelength $\lambda_p = 940$ nm
- Good spectral matching to si-photodetector
- Radiant angle: 80°

Notes :

1. Tolerance is ± 0.25 mm (.010") unless otherwise noted.
2. Protruded resin under flange is 1.5 mm (.059") max.
3. Lead spacing is measured where the leads emerge from the package.

Absolute Maximum Ratings

@ $T_A = 25^\circ\text{C}$

Parameter	Maximum Rating	Unit
Power Dissipation	120	mW
Peak Forward Current	1	A
Continuous Forward Current	100	mA
Reverse Voltage	5	V
Operating Temperature Range	-55°C to $+100^\circ\text{C}$	
Storage Temperature Range	-55°C to $+100^\circ\text{C}$	
Lead Soldering Temperature	260°C for 5 seconds	

Optical-Electrical Characteristics

@ $T_A=25^\circ\text{C}$

Parameter	Test Conditions	Symbol	Min.	Typ .	Max.	Unit
Radiant Intensity	$I_F=20\text{mA}$	I_e	0.2	0.7	-	mW/sr
Forward Voltage	$I_F=50\text{mA}$	V_F	-	1.32	1.50	V
Reverse Current	$V_R=5\text{V}$	I_R	-	-	100	μA
Peak Wavelength	$I_F=20\text{mA}$	λ	-	940	-	nm
Spectral Bandwidth	$I_F=20\text{mA}$	$\Delta\lambda$	-	50	-	nm
View Angle	$I_F=20\text{mA}$	$2\theta_{1/2}$	-	120	-	deg .

Typical Optical-Electrical Characteristic Curves

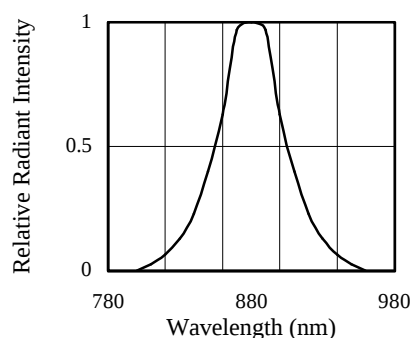


FIG.1 SPECTRAL DISTRIBUTION

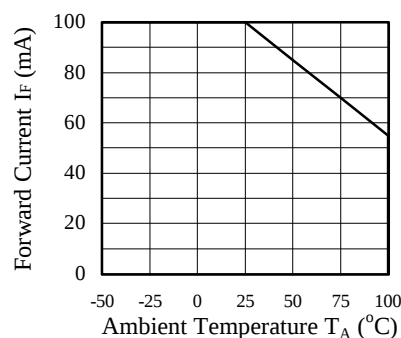


FIG.2 FORWARD CURRENT VS. AMBIENT TEMPERATURE

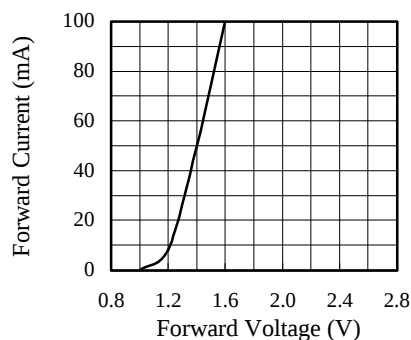


FIG.3 FORWARD CURRENT VS. FORWARD VOLTAGE

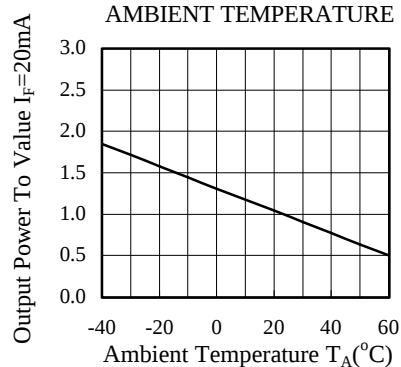


FIG.4 RELATIVE RADIANT INTENSITY VS. AMBIENT TEMPERATURE

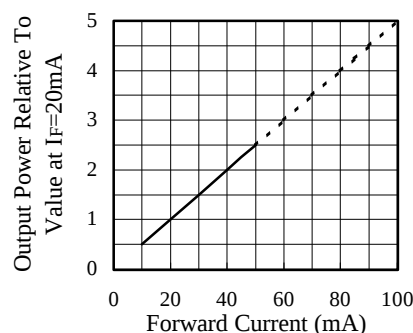


FIG.5 RELATIVE RADIANT INTENSITY VS. FORWARD CURRENT

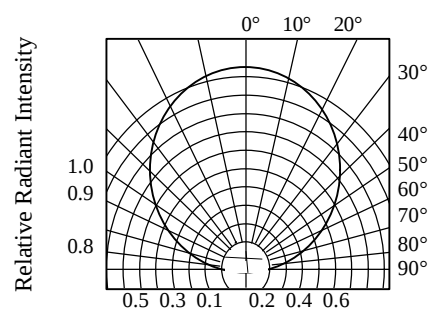


FIG.6 RADIATION DIAGRAM